

FEATURE

- Ultra-thin, thickness 0.7mm
- Leadless type
- High precision characteristic covering up to high frequency range
- Designed for automatic mounting and reflow soldering
- Emboss taping specification
- The best choice of Bluetooth wireless communication sets, DSN, PDA and mobile phone.

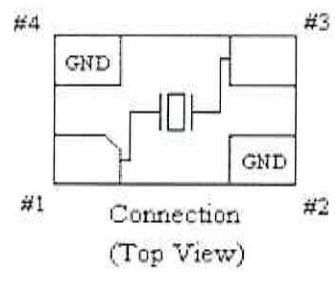
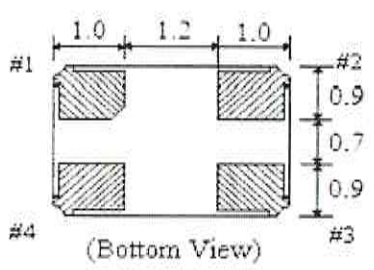
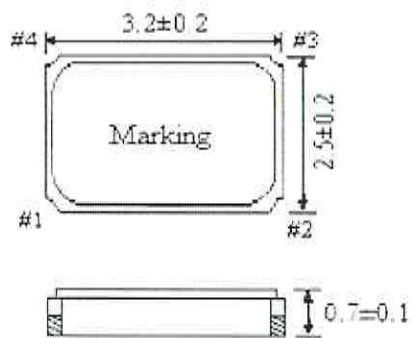


ELECTRICAL SPECIFICATIONS

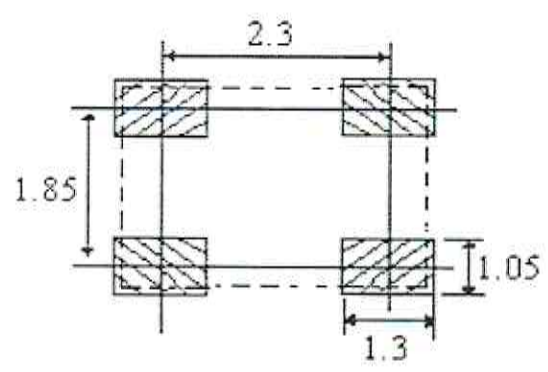
Output Frequency Range	8.000MHz
Mode	Fundamental
Frequency Tolerance (at 25°C)	±50ppm
Frequency Stability Over Operating Temperature Characteristics	±50ppm
Operating Temperature Range	-40°C to +85 °C
Storage Temperature Range	-55°C to +125 °C
Electrostatic Capacitance	3.0pF Max
Driver Level (Typical)	10μW~100μW
Load Capacitance(C _L)	8pF
EQUIVALENT SERIES RESISTANCE (ESR)	500Ω Max
Aging @25°C 1 st year (Max)	±5ppm/year
Shock Resistance	Drop test of 3 times on 2mm stainless plate from 75cm height

REMARK: SPECIFICATIONS SUBJECT TO CHANGE WITHOUT PRIOR NOTICE. PLEASE CONFIRM WITH OUR SALES ENGINEER.

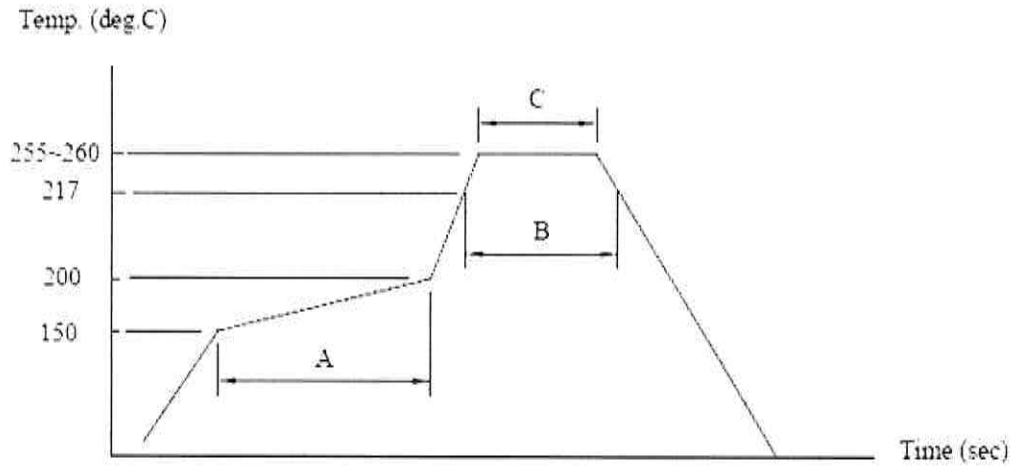
DIMENSION Unit: mm



Recommended Soldering Pattern



Soldering Reflow



(A)—Preheating area : 150~200°C. 60~120sec.

(B)—Heating area : 217°C. 60~150sec.

(C)—Peak temperature : 255~260°C. 30sec. Max.

Ramp-up rate (217→260°C) : 3°C/sec. Max.

Ramp-down rate (260→217°C) : 6°C/sec. Max.

Time 25°C—260°C : 480sec. Max.

*Reference JEDEC J-STD-020

TAPE & REEL

